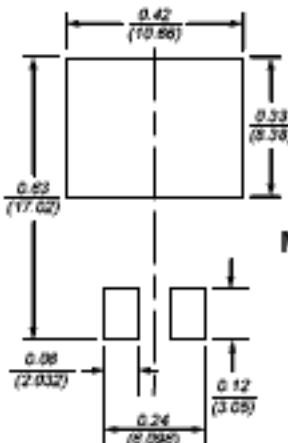
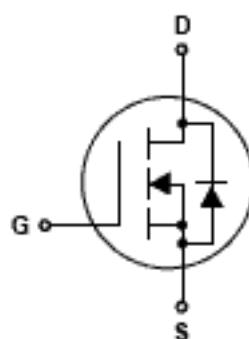
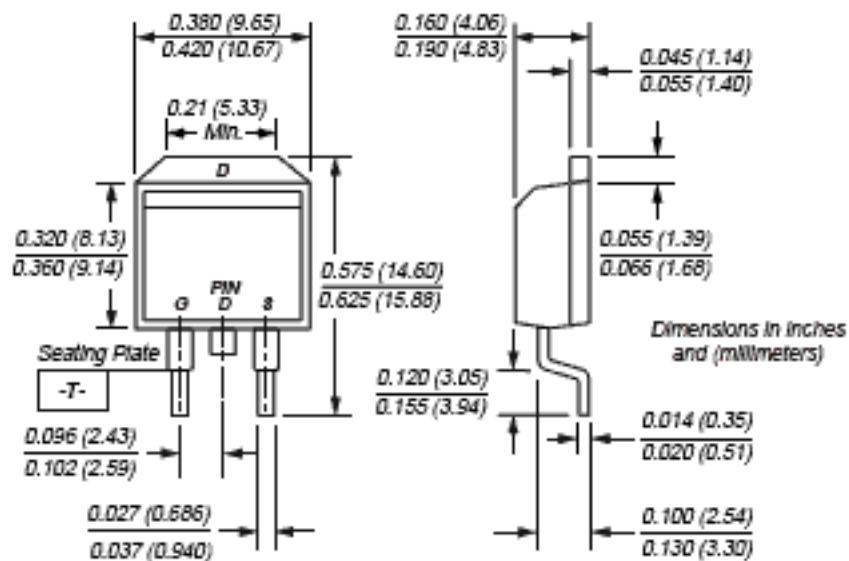




N-Channel Enhancement-Mode MOSFET

V_{DS} 30V $R_{DS(ON)}$ 8m Ω I_D 70A

TO-263AB



Mounting Pad Layout

Mechanical Data

- Case: JEDEC TO-263 molded plastic body
- Terminals: Leads solderable per MIL-STD-750, Method 2026
- High temperature soldering guaranteed: 250°C/10 seconds at terminals
- Mounting Position: Any Weight: 1.3g

Features

- Advanced Trench Process Technology
- High Density Cell Design for Ultra Low On-Resistance
- Specially Designed for Low Voltage DC/DC Converters
- Fast Switching for High Efficiency

Maximum Ratings and Thermal Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ⁽¹⁾	I_D	70	A
Pulsed Drain Current	I_{DM}	200	
Maximum Power Dissipation	P_D	62.5 25	W
$T_c = 25^\circ\text{C}$ $T_c = 100^\circ\text{C}$			
Operating Junction and Storage Temperature Range	T_J, T_{Stg}	-55 to 150	°C
Lead Temperature (1/8" from case for 5 sec.)	T_L	275	°C
Junction-to-Case Thermal Resistance	R_{JC}	2.0	°C/W
Junction-to-Ambient Thermal Resistance ⁽²⁾	R_{JA}	40	°C/W

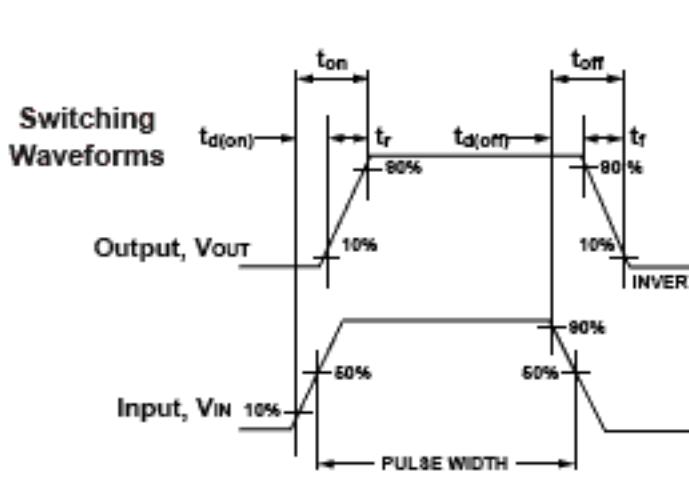
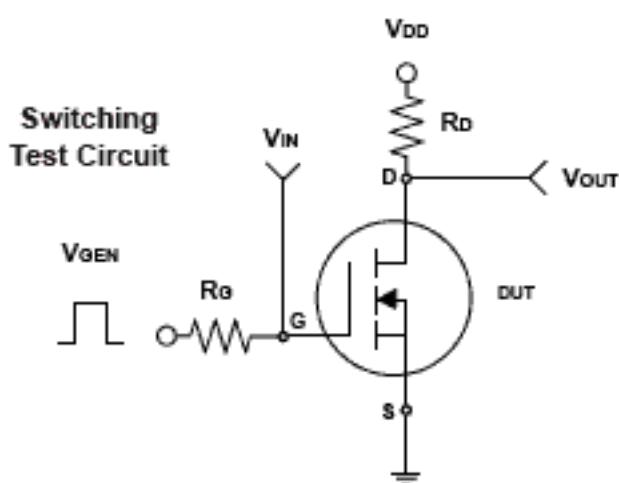
Notes: (1) Maximum DC current limited by the package

(2) 1-in² 2oz. Cu PCB mounted

N-Channel Enhancement-Mode MOSFET
Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = 250\mu\text{A}$	30	—	—	V
Gate Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_D = 250\mu\text{A}$	1.0	—	3.0	V
Gate-Body Leakage	I_{GSS}	$\text{V}_{\text{DS}} = 0\text{V}, \text{V}_{\text{GS}} = \pm 20\text{V}$	—	—	± 100	nA
Zero Gate Voltage Drain Current	I_{DSSS}	$\text{V}_{\text{DS}} = 30\text{V}, \text{V}_{\text{GS}} = 0\text{V}$	—	—	1	μA
On-State Drain Current ⁽¹⁾	$\text{I}_{\text{D(on)}}$	$\text{V}_{\text{DS}} \geq 5\text{V}, \text{V}_{\text{GS}} = 10\text{V}$	70	—	—	A
Drain-Source On-State Resistance ⁽¹⁾	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}} = 10\text{V}, \text{I}_D = 35\text{A}$	—	8	8	$\text{m}\Omega$
		$\text{V}_{\text{GS}} = 4.5\text{V}, \text{I}_D = 30\text{A}$	—	9	11	
Forward Transconductance ⁽¹⁾	g_{fs}	$\text{V}_{\text{DS}} = 15\text{V}, \text{I}_D = 35\text{A}$	—	61	—	S
Dynamic						
Total Gate Charge	Q_g	$\text{V}_{\text{DS}} = 15\text{V}, \text{V}_{\text{GS}} = 5\text{V}, \text{I}_D = 35\text{A}$	—	34	48	nC
Gate-Source Charge	Q_{gs}	$\text{V}_{\text{DS}} = 15\text{V}, \text{V}_{\text{GS}} = 10\text{V}$ $\text{I}_D = 35\text{A}$	—	63	95	
Gate-Drain Charge	Q_{gd}		—	11	—	
Turn-On Delay Time	$t_{\text{d(on)}}$	$\text{V}_{\text{DD}} = 15\text{V}, \text{R}_L = 15\Omega$ $\text{I}_D \geq 1\text{A}, \text{V}_{\text{GEN}} = 10\text{V}$	—	9	14	ns
Rise Time	t_r		—	9	14	
Turn-Off Delay Time	$t_{\text{d(off)}}$		—	100	187	
Fall Time	t_f		—	31	62	
Input Capacitance	C_{iss}	$\text{V}_{\text{GS}} = 0\text{V}$ $\text{V}_{\text{DS}} = 15\text{V}$ $f = 1.0\text{MHz}$	—	3400	—	pF
Output Capacitance	C_{oss}		—	618	—	
Reverse Transfer Capacitance	C_{rss}		—	300	—	
Source-Drain Diode						
Max Diode Forward Current	I_S	—	—	—	35	A
Diode Forward Voltage ⁽¹⁾	V_{SD}	$\text{I}_S = 35\text{A}, \text{V}_{\text{GS}} = 0\text{V}$	—	0.9	1.3	V

Note: (1) Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$



N-Channel Enhancement-Mode MOSFET

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 – Output Characteristics

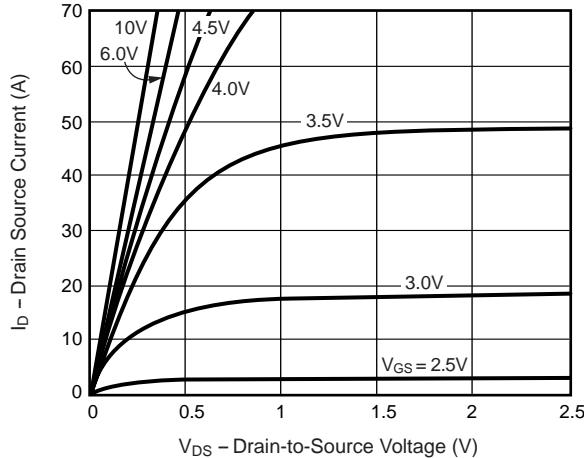


Fig. 2 – Transfer Characteristics

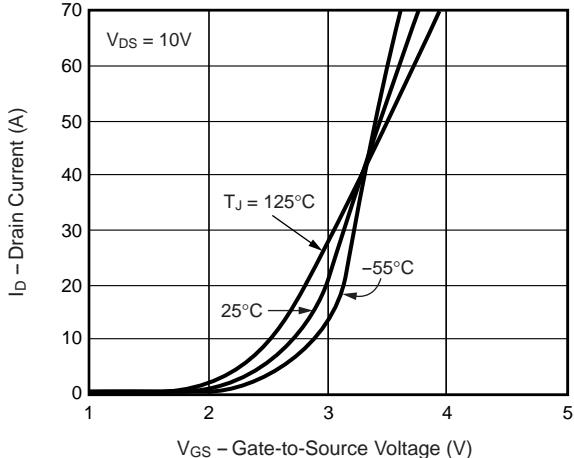


Fig. 3 – Threshold Voltage vs. Temperature

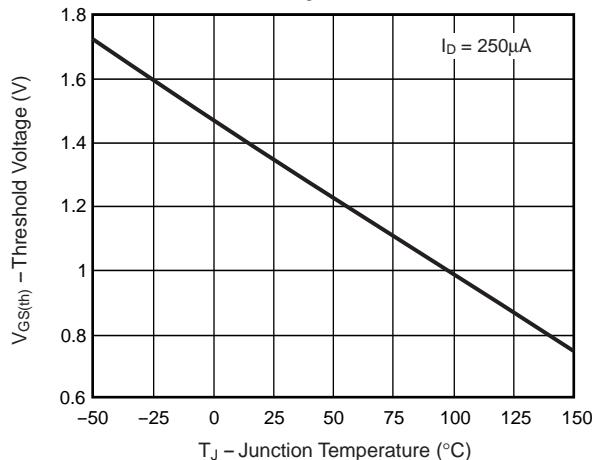


Fig. 4 – On-Resistance vs. Drain Current

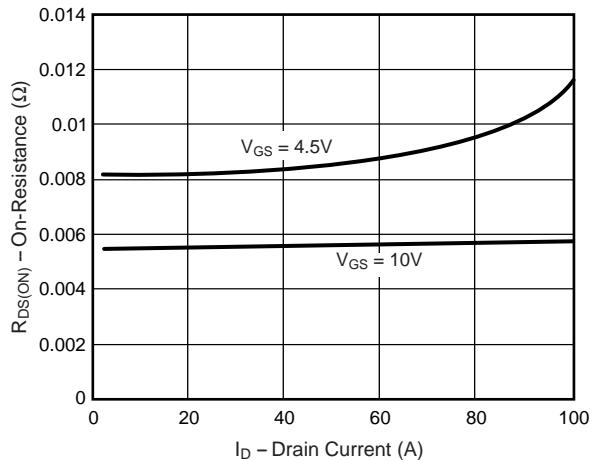
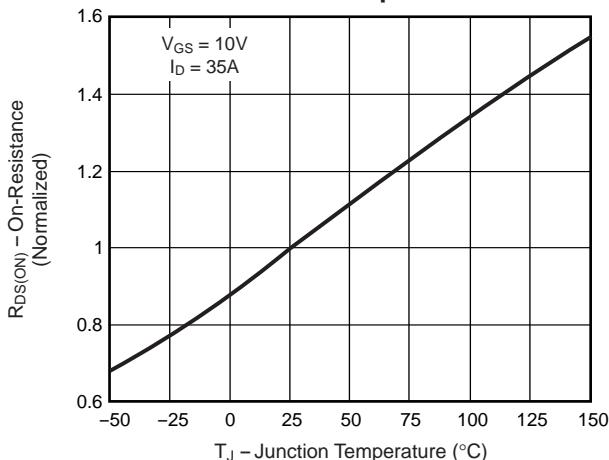


Fig. 5 – On-Resistance vs. Junction Temperature



N-Channel Enhancement-Mode MOSFET

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

**Fig. 6 – On-Resistance vs.
Gate-to-Source Voltage**

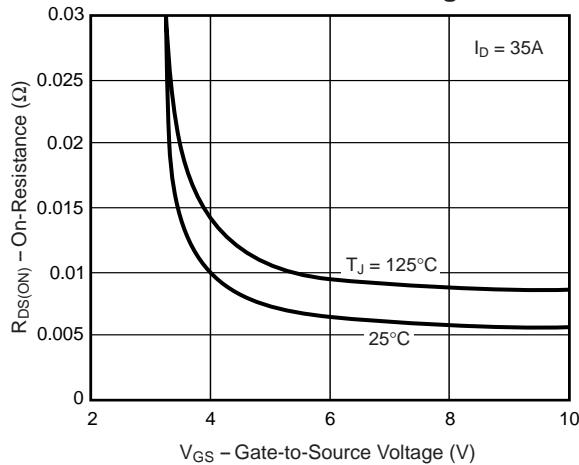


Fig. 7 – Gate Charge

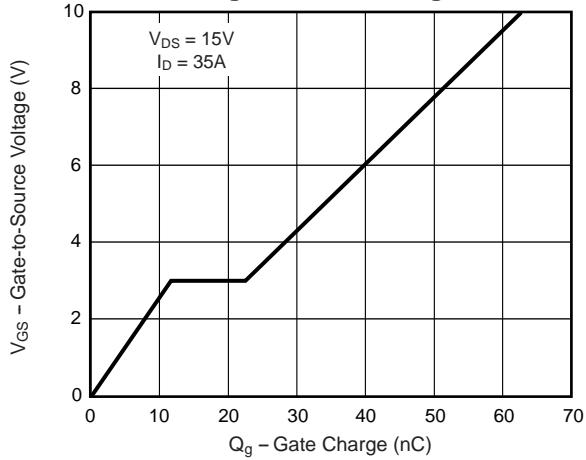


Fig. 8 – Capacitance

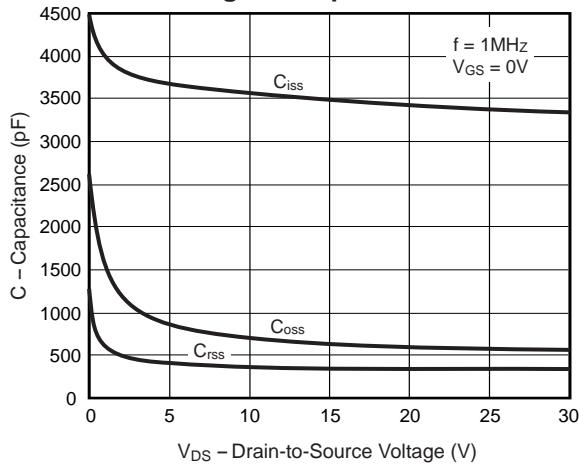
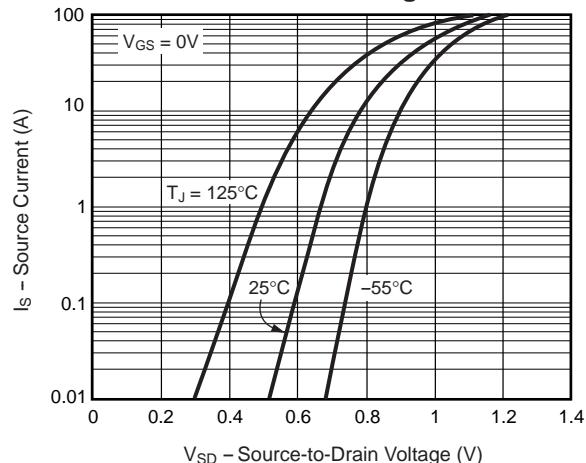


Fig. 9 – Source-Drain Diode Forward Voltage



N-Channel Enhancement-Mode MOSFET

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 10 – Breakdown Voltage vs. Junction Temperature

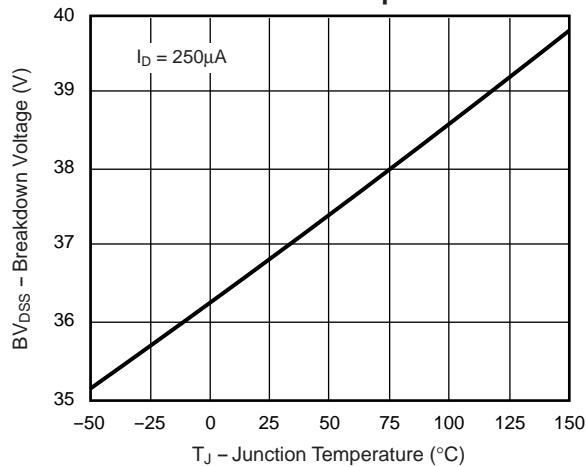


Fig. 11 – Thermal Impedance

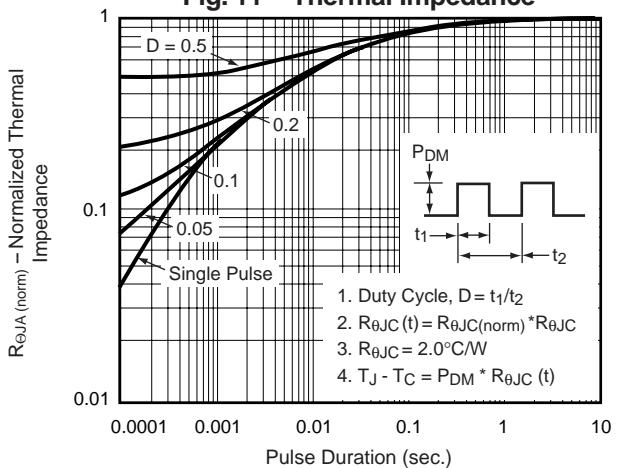


Fig. 12 – Power vs. Pulse Duration

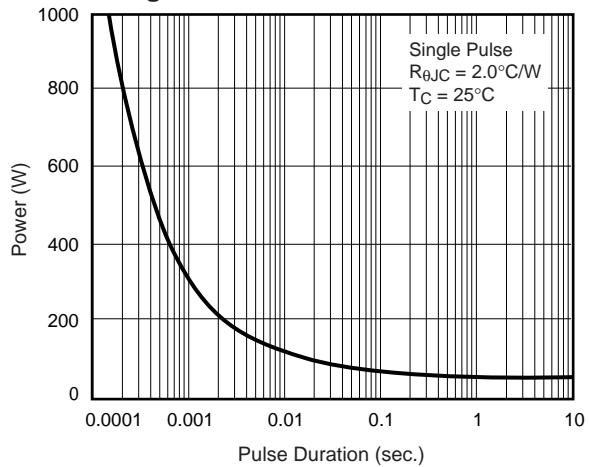
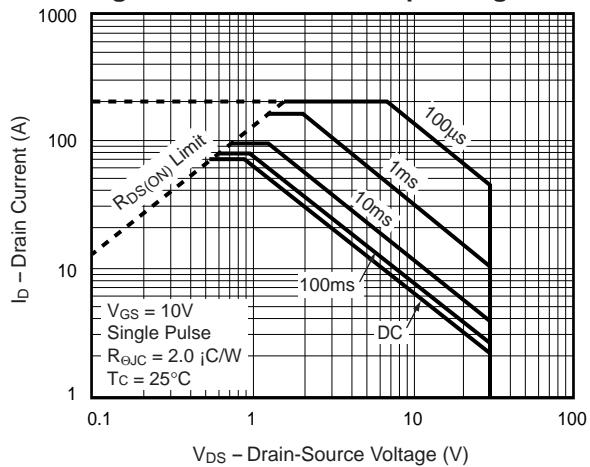


Fig. 13 – Maximum Safe Operating Area



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